

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L8	1888089	substrate or substrates or wafer or wafers	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:46
2	BRS	L9	4841760	inject\$6 or spray\$6 or immers\$6 or introduc\$6 or squirt\$6 or scatter\$6 or spurt\$6 or spew\$6 or cover\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:49
3	BRS	L10	3003901	(diisocyanate adj monomers) or (diisocynate adj end-capped adj complicant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj3 polymer) or water or <u>"H.sub.2O"</u> or (polymer\$6 near2 foam46)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:54
4	BRS	L11	8311	9 near8 10 near8 8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:55
5	BRS	L12	731674	interconnect\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:56

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L13	506239	stack\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:56
7	BRS	L14	27395	microelectronic or micro-electronic	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:56
8	BRS	L15	0	11 same 12 same 13	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:56
9	BRS	L16	215665 2	react\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:57
10	BRS	L17	724	11 same 16	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:57

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L18	16	17 same 12	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 12:59
12	BRS	L19	108501 43	between or middle or link\$4 or connect\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 13:00
13	BRS	L20	143	17 same 19	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/27 13:05

L 21 flip chip or BGA or ball. wdg

grid or (IC or device or package or
die or die - - -) near 8 (board
or substrate or wafer or pcb) or MCM?
or multi-chip or interposers or
leadframes

L 24 L18 near ⁸4 (billing or filler or infill or insulator
or support)
L 25 (L21 near 4 L18) (+i) - if want to reduce this

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	525425	(flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:12
2	BRS	L2	302853 3	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:17
3	BRS	L4	55483	2 near4 (filling or filler or infill or insulat\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:16
4	BRS	L6	1429	4 and 1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:16
5	BRS	L5	140	4 same 1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:16

	Type	L #	Hits	Search T xt	DBs	Time Stamp
6	BRS	L7	302663 3	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:17
7	BRS	L8	103082	7 near4 (filling or filler or infill or insulat\$4 or support\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:19
8	BRS	L10	265	8 same 1	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/28 19:19

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L27	549	polymerization near4 substrates	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:06
2	BRS	L28	78	27 same reaction	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:23
3	BRS	L31	80	reaction near4 (polymer adj foam)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:27
4	BRS	L32	13	(polymer adj foam) near8 substrates	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:39
5	BRS	L33	46896	polymeriz\$4 same reaction	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:39

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L34	588	33 same substrates	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 13:39
7	BRS	L35	171	34 same materials	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 14:06
8	BRS	L36	733364	interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 14:06
9	BRS	L38	69	35 and 36	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/29 14:06